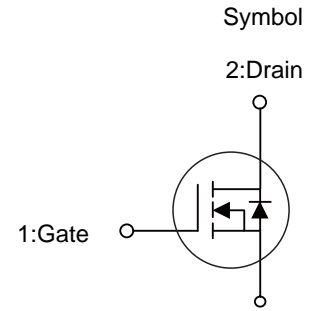


■ PRODUCT CHARACTERISTICS

$V_{DSS}$	-30V
$R_{DS(ON)}$ Typ(@ $V_{GS}=-10V$ )	5m $\Omega$
$R_{DS(ON)}$ Typ(@ $V_{GS}=-4.5V$ )	6.6m $\Omega$
$I_D$	-80A



■ APPLICATIONS

- \* Electronic lamp ballasts based on half bridge
- \* Load Switching, Quick/Wireless Charge.
- \* Motor Driving

■ FEATURE

- \* Low Gate Charge
- \* Pb-Free Lead Plating



TO-252

■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT80P03D	TO-252	2500 pieces/Reel

■ ABSOLUTE MAXIMUM RATINGS( $T_A=25^{\circ}C$ , unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DSS}$	-30	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current Continuous(@ $V_{GS}=-10V, T_A=25^{\circ}C$ )	$I_D$	-80	A
Drain Current Pulsed	$I_{DM}$	-320	A
Avalanche Energy	$E_{AS}$	380	mJ
Power Dissipation	$P_D$	65	W
Junction Temperature	$T_J$	+150	$^{\circ}C$
Storage Temperature	$T_{STG}$	-55~ +150	$^{\circ}C$

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	$R_{thJC}$	1.92	$^{\circ}C/W$

■ ELECTRICAL CHARACTERISTICS ( $T_C=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	$V_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Drain to Source Leakage Current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate to Source Forward Leakage	$I_{GSS(F)}$	$V_{GS}=+20V, V_{DS}=0V$	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	$V_{GS}=-20V, V_{DS}=0V$	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-20A$	-	5	6	m $\Omega$
		$V_{GS}=-4.5V, I_D=-10A$	-	6.6	8	m $\Omega$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.6	-2.5	V
Dynamic characteristics						
Gate capacitance	$R_g$	$V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$	-	11	-	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS}=-10V, I_D=-3A$	-	17	-	S
Input Capacitance	$C_{iss}$	$V_{DS}=-20V, V_{GS}=0V$ $f=1.0\text{MHz}$	-	3300	-	pF
Output Capacitance	$C_{oss}$		-	421	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	318	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=-10V, V_{DS}=-15V,$ $I_D=-30A, R_G=2.4\Omega$	-	17	-	ns
Rise Time	$t_r$		-	143	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	98	-	ns
Fall Time	$t_f$		-	106	-	ns
Total Gate Charge	$Q_g$	$I_D=-30A, V_{DS}=-15V$ $V_{GS}=-10V$	-	125	-	nC
Gate to Source Charge	$Q_{gs}$		-	26	-	nC
Gate to Drain("Miller") Charge	$Q_{gd}$		-	20	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	$I_S$		-	-	-80	A
Maximum Pulsed Current(Body Diode)	$I_{SM}$		-	-	-320	A
Diode Forward Voltage	$V_{SD}$	$I_{SD}=-1A, V_{GS}=0V$	-	-0.7	-1.2	V
Reverse Recovery Time	$t_{rr}$	$I_{SD}=-20A, T_J=25^{\circ}\text{C}$ $di/dt=100A/\mu s$	-	55	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	73	-	nC

■ TYPICAL CHARACTERISTICS

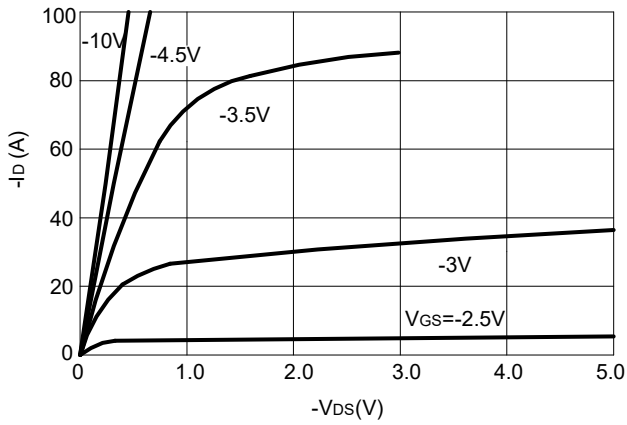


Figure 1: Output Characteristics

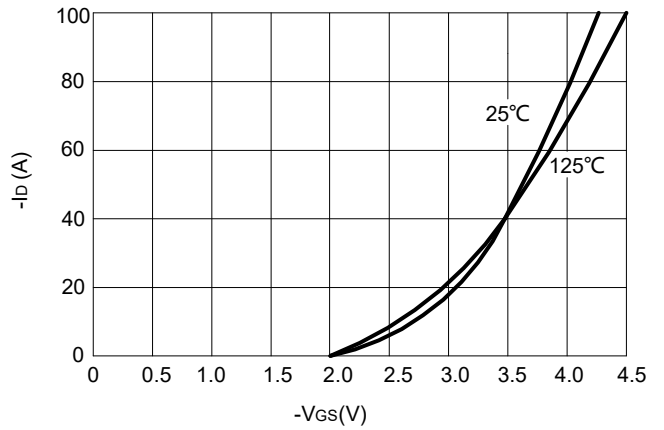


Figure 2: Typical Transfer Characteristics

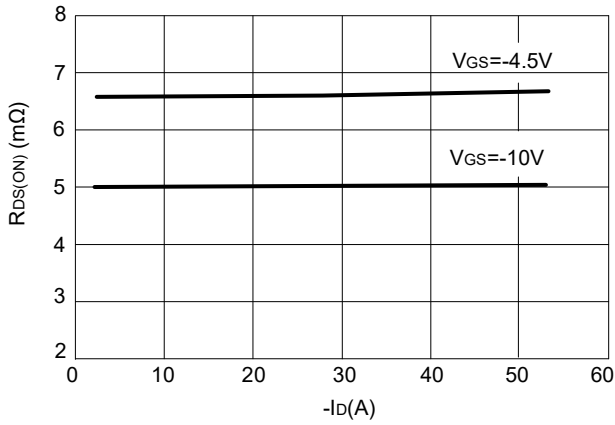


Figure 3: On-resistance vs. Drain Current

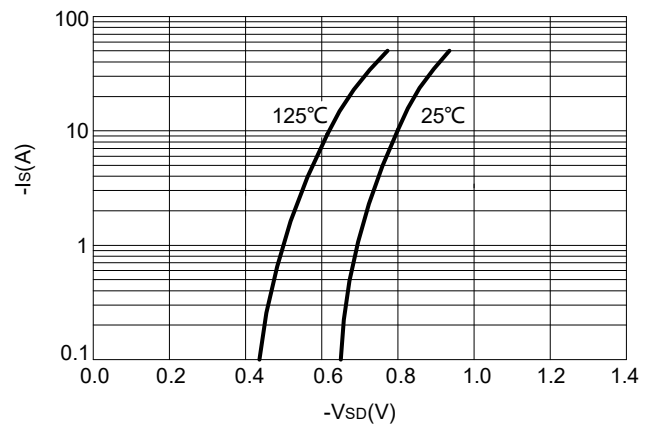


Figure 4: Body Diode Characteristics

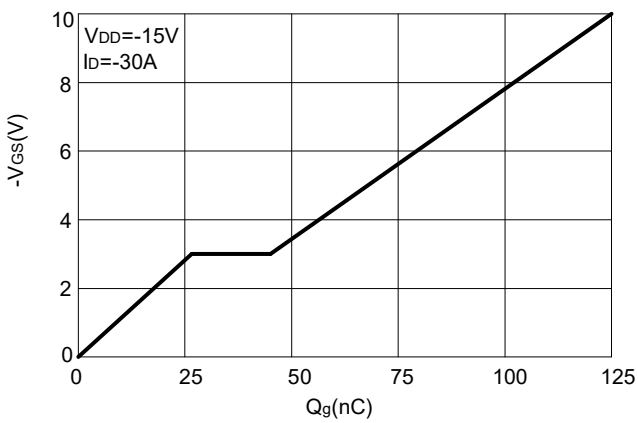


Figure 5: Gate Charge Characteristics

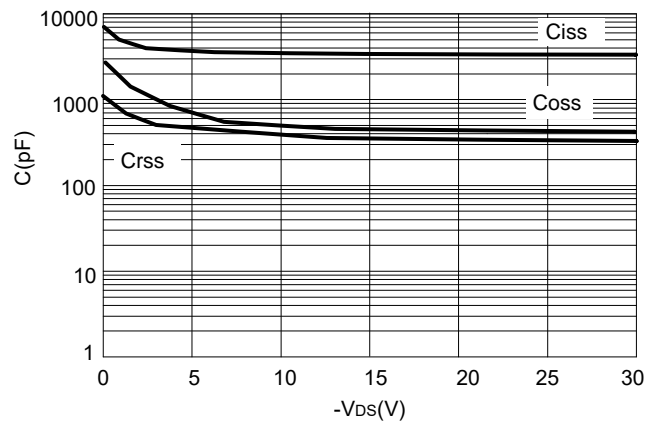


Figure 6: Capacitance Characteristics

■ TYPICAL CHARACTERISTICS(Cont.)

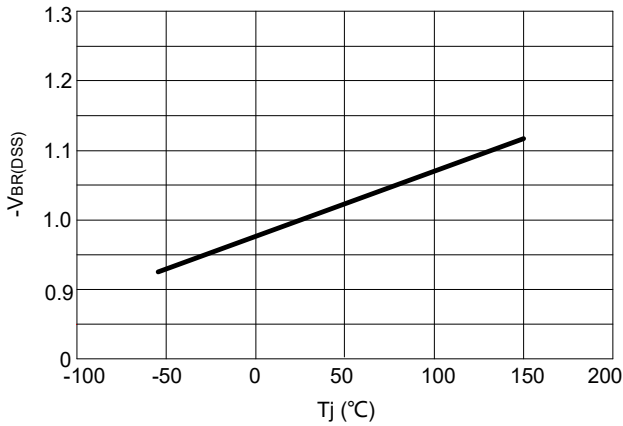


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

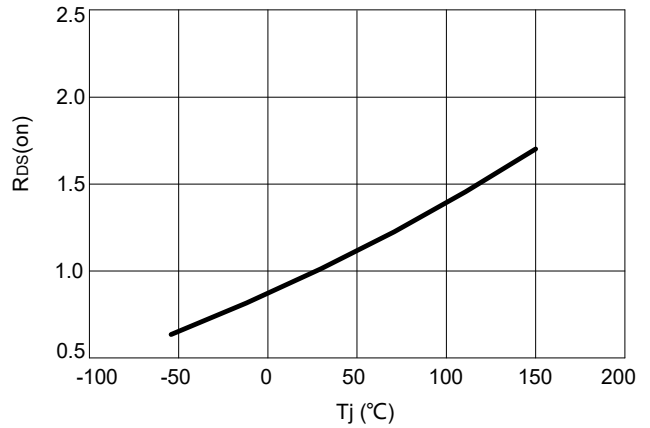


Figure 8: Normalized on Resistance vs. Junction Temperature

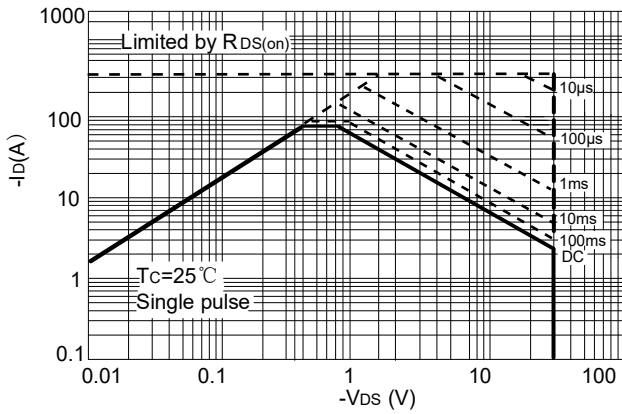


Figure 9: Maximum Safe Operating Area

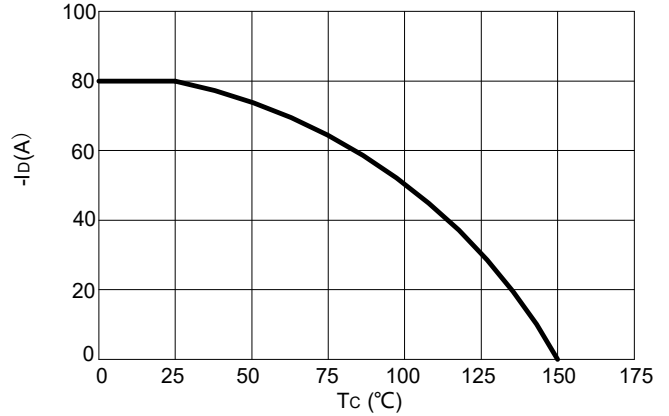


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

■ TO-252 PACKAGE OUTLINE DIMENSIONS

